



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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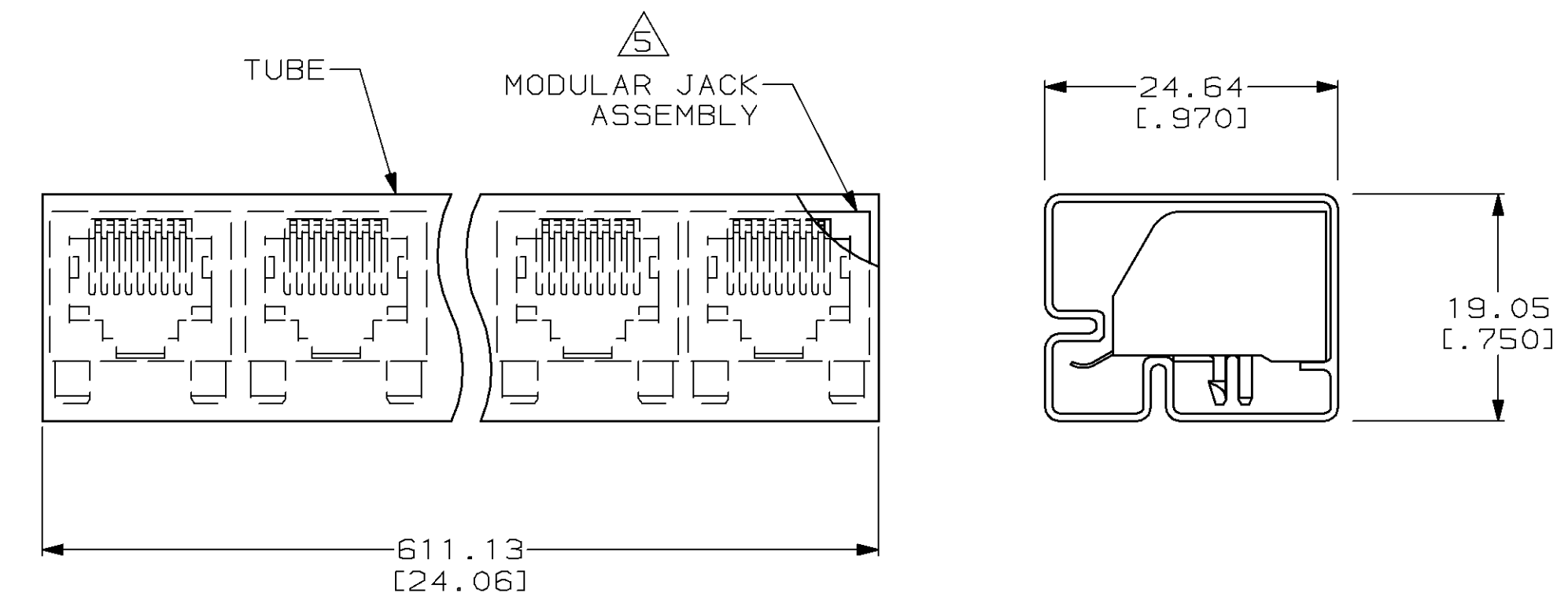
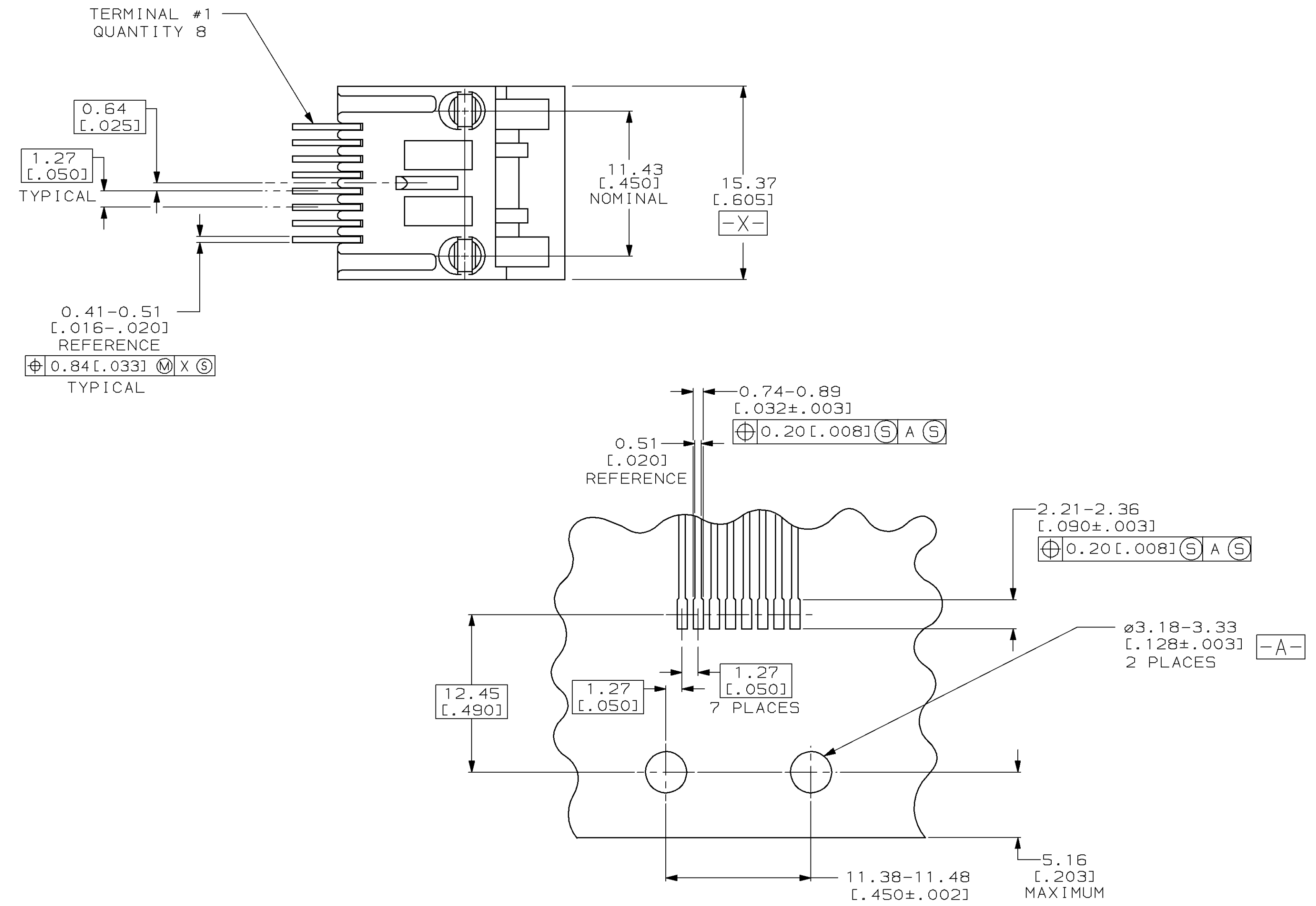
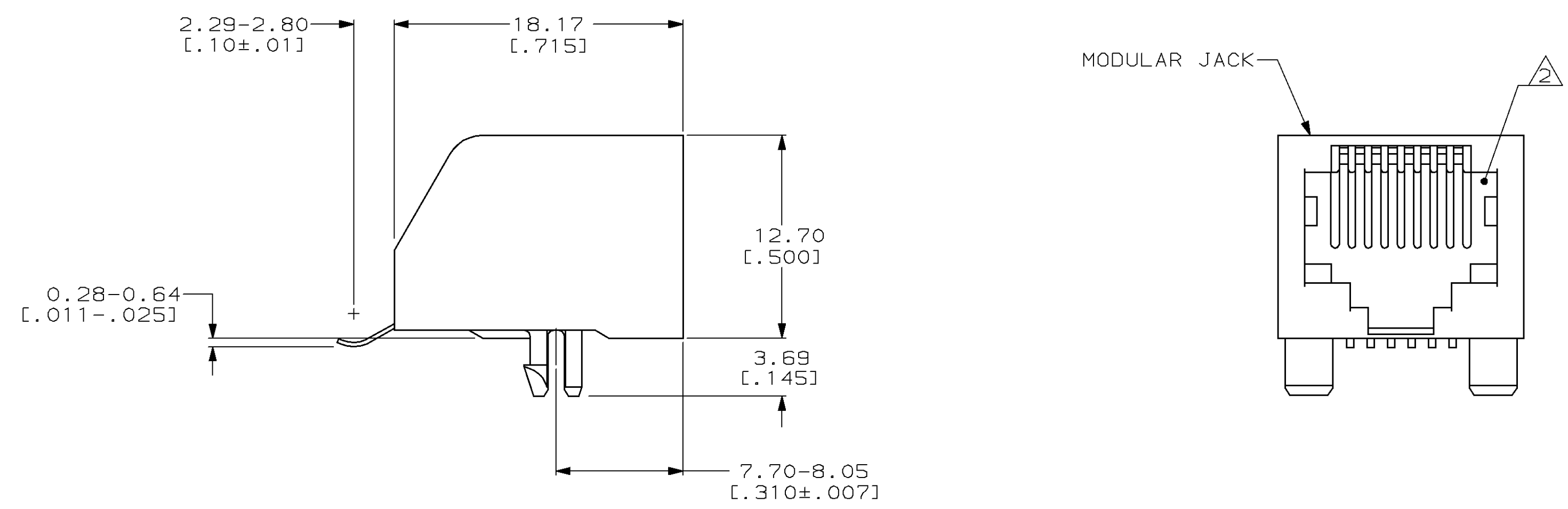
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LOC		DIST		P		F		ZONE		LTR		REVISIONS			
AA	22											DESCRIPTION	DATE	APPD	
												P	REV; EC 0502-0711-97	230CT97	05

- △ MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 V0, BLACK.  
 TERMINAL - 0.36 [0.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [0.00050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [0.00150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- 4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [0.062±.005] THICK PRINTED CIRCUIT BOARD.
- △ ASSEMBLIES ARE PACKAGED 36 IN A TUBE.
- △ ASSEMBLIES ARE BULK PACKAGED.



DETAIL A  
SCALE 2:1

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON:		DR 9-28-95 D. STRAUSSER	8		555764-3
2 PLC DEC ± -		CHK 10-17-95 N. JONES	8		555764-1
3 PLC DEC ± -		APPD 10-23-95 J. TONEY	PACKAGED	NUMBER OF TERMINALS	PART NO
ANGLES ± -		APPD 10-24-95 H. MCGRATHS	AMP Incorporated Harrisburg, PA 17105-3608		
MATERIAL	△	PRODUCT SPEC 108-1163	NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT		
FINISH	△	APPLICATION SPEC 114-6040	SIZE D	CAGE CODE 00779	DRAWING NO C=555764
WEIGHT -		SCALE 4:1	SHEET 1 OF 1		

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.